

International Technical Conference and Smart PCB: AI Trends & Innovations Conference will be concurrently held with the 2024 HKPCA Show in Hall 5 & 6 at Shenzhen World Exhibition & Convention Center (Bao'an). An array of the hottest topics and market trends will be shared by industry experts from the leading enterprises and academic representatives from the top institution in the world which connect Industry and academia to advance knowledge and create a skilled workforce. Attending the conference, you can gain the first-hand information with the latest technologies of PCB Industry.

国际技术会议和 智造PCB: AI趋势与创新技术会议 将与2024 国际电子电路(深圳)展览会同期在深圳国际会展中心(宝安)5、6号馆举行。行业专家、业内知名企业代表及学术研究专家将与大家分享热门议题和线路板市场最新动态, 为您引进新思维, 走在行业最前沿。通过来自学术界及业界专家的分享, 提升行业水平及培养高技术人才。请即预先登记, 获得PCB行业的最新技术及第一手资料。

International Technical Conference 国际技术会议

Hall 6
Shenzhen World Exhibition &
Convention Center (Bao'an)
深圳国际会展中心(宝安)六号馆

Smart PCB: AI Trends & Innovations Conference 智造PCB: AI趋势与创新技术会议

Hall 5
Shenzhen World Exhibition &
Convention Center (Bao'an)
深圳国际会展中心(宝安)五号馆

Notes:

- Free admission for audiences with the badge of 2024 HKPCA Show.
- Pre-registration is required. Walk-ins will be accepted based on availability.
- Limited seats available on a first-come-first-served basis.
- The final schedule is subject to the actual arrangements of the day.
- Conference to be conducted in Chinese Mandarin unless otherwise specified.

备注:

- 凭2024国际电子电路(深圳)展览会入场证可免费入场参加。
- 演讲为预约制。将因应会议当天情况开放现场报名。
- 场地位置有限, 先到先得。
- 会议议程以活动当天的实际安排为准。
- 除非另有说明, 会议将以中文进行。

REGISTER NOW!
立即报名



Enquiries
查询

HKPCA 香港线路板协会
(852) 2155 5099, (86) 755 8624 0033
secretary@hkpc.org



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XACT

Version: 13-Nov-24





CONFERENCE AGENDA 会议议程

2024.12.04 Wednesday (星期三)

| Time 时间 | International Technical Conference 国际技术会议 (Hall 6) | Smart PCB: AI Trends & Innovations Conference 智造PCB: AI趋势与创新技术会议 (Hall 5) |
|---------------|--|--|
| 10:50 – 11:00 | Welcome Speech Canice CHUNG, Chairman, HKPCA 欢迎辞 钟泰强 — 香港线路板协会会长 | |
| 11:00-11:30 | PCB Market and Technology Developments for AI Server Systems # Dr. Shiu-Kao CHIANG, Managing Partner, Prismark AI服务器系统的PCB市场和技术发展# 姜旭高博士 — Prismark合作伙伴 | One Digital Foxconn Towards the AI Era Jin LI, Senior Manager, Foxconn Technology Group 迈向AI世纪的One Digital Foxconn 李锦光 — 富士康科技集团资深经理 |
| 11:30 – 12:00 | | AI-era Dell Accelerates Electronic PCB Industry from Idea to Innovation Richard LI, Senior Manager, Dell Technologies AI时代戴尔科技加快电子PCB行业从构想到实现创新 李炜 — 戴尔科技集团终端产品组合作伙伴与行业方案业务高级经理 |
| 12:00 – 12:30 | Technology Status and Quality Challenges of Communication PCB # Fulin ZENG, Senior Engineer and Senior Technical Quality Expert, ZTE 通讯产品PCB技术动态和质量挑战# 曾福林 — 中兴通讯高级工程师, 技术质量资深专家 | Artificial Intelligence – Design and Manufacturing Opportunities and Challenges in the PCB Industry* Erkko HELMINEN, Senior Manager of Commercial Technology, TTM Technologies 人工智能 — PCB行业设计及制造的机遇和挑战* Erkko HELMINEN — TTM集团商用技术部高级经理 |
| 12:30 - 13:30 | 午休时间 Lunch Break | |
| 13:30 – 14:30 | A New Flex Electroless Nickel Chemistry for ENIG and ENEPIG Applications Ryan TAM, Business Director, MacDermid Alpha Electronics Solutions FPC专用的化镍金或镍钎金制程: 新型软镍药水 谈国志 — 麦德美爱法电子解决方案业务总监 | |
| 14:00 – 14:30 | | Artificial Intelligence and PCB Outlook: Computing as the Foundation and Application as the Spear Jack DING, Senior Vice President Research Dept, CITIC Securities 人工智能与PCB展望: 算力为基, 应用为矛 丁奇 — 中信证券研究部高级副总裁 |
| 14:30 – 15:00 | On-device AI Supports New Development Opportunities for PCB Development Vincent WANG, Group Technical Director, Shenzhen Kinwong Electronic Co., Ltd. 端侧AI助力PCB发展新机遇 王俊 — 深圳市景旺电子股份有限公司集团技术总监 | AI Empowers the High-quality Development of the PCB Industry Simon YU, Executive President, Shenzhen Intelligent Manufacturing Industry Promotion Association; AI赋能PCB产业高质量发展 喻波 — 深圳市智能制造产业促进会常务会长 |
| 15:00 – 15:30 | The Driving Forces and Prospects of IC Packaging Substrate Development Dr. Rambo SUN, PH.D/CTO, Bomim Electronics Co., Ltd. IC封装基板发展驱动力与前景 孙炳合博士 — 博敏电子股份有限公司首席技术官 | From Data to Artificial Intelligence: The Transformation Journey of AI Technology in PCB Industry Harold CHENG, General Manager, PROFET AI 从数据到人工智能: AI技术在PCB产业中的转型之路 郑诗怀 — 上海颀纶科技软件有限公司总经理 |
| 15:30 – 16:00 | Challenges and Solutions for PCB Manufacturing Posed by 224G High-Speed Signals Dr. Yuuta TANG, Technical expert, Zhuohai Founder Technology High Density Electronic Co., Ltd. 224G高速信号对PCB制造提出的挑战及解决方案 唐耀博士 — 珠海方正科技高密电子有限公司技术专家 | Liquid Chromatography-electrochemistry Combined Detection of Plating Solution Additives Junwei WU, Postgraduate, School of Chemistry, Sun Yat-sen University 液相色谱-电化学联用检测镀液添加剂 吴俊伟 — 中山大学化学学院硕士研究生 Research on Replacing Salt Spray Test with Tafel Test Haocheng LIU, Postgraduate, School of Chemistry, Sun Yat-sen University 塔菲尔测试替代盐雾试验的研究 刘浩衡 — 中山大学化学学院硕士研究生 |
| 16:00 – 16:30 | Study on the Influence of PCB Solder Resist Materials on Solder Joint Formation Quality Li ZHAO, Senior Process Expert and Project Manager, ZTE Corporation PCB阻焊材料对焊点成型质量的影响研究 赵丽 — 中兴通讯股份有限公司工艺资深专家、项目经理 | AI Accelerates PCB Pre-manufacturing Engineering Design and Precise Quotations Towers GUO, General Manager, Shenzhen Yimeike Software Co., Ltd., AI赋能PCB制前工程设计和精准报价 郭套山 — 深圳市易美科软件有限公司总经理 |

Conference duration is 45 mins
* Conference to be conducted in English

会议时间为45分钟
* 会议以英文进行





CONFERENCE AGENDA 会议议程

2024.12.05 Thursday (星期四)

| Time 时间 | International Technical Conference 国际技术会议 (Hall 6) | Smart PCB: AI Trends & Innovations Conference 智造PCB: AI趋势与创新技术会议 (Hall 5) |
|---------------|--|--|
| 10:30 – 11:00 | Implementation of Carbon Trading and ESG in China and Overseas Markets Prof. Felix CHUNG, Adjunct Professor in the Chinese University of HK and City University of HK, HKCTC Founder 国内外碳权交易与ESG推行的执行方案 钟国斌教授 — 香港中文大学及香港城市大学兼任教授; 香港碳贸易中心创办人 | IPC Factory of the Future Standards Empower AI-enabled PCB Manufacturing Chuck LI, Standards Director, IPC IPC未来工厂标准助力AI赋能PCB生产 李金山 — IPC国际电子工业联接协会 标准总监 |
| 11:00-11:30 | Introduction of LCMP Carbon Reduction Methodology and Samples of Energy Saving Technologies # Luther WONG, Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA LCMP低碳制造减碳方法学介绍及节能技术案例 # 王乐得 — 思捷环保科技有限公司创办人及行政总裁; 香港线路板协会副会长兼秘书长 | PCB Process and Simulation Analysis of AI Products Gang HUANG, SI Research Manager, Shenzhen Edadoc Technology Co., Ltd. AI产品的PCB工艺与仿真分析 黄刚 — 深圳市一博科技股份有限公司SI研究部经理 |
| 11:30 – 12:00 | ESG Panel Discussion # Moderator: Luther WONG, Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA Guests: Hongping ZHA, Environment Engineering Department Manager, Jiangxi Redboard Technology Co., Ltd. Qiangdong ZHANG, Manger, Sunshine Global Circuits Co., Ltd. KK ZHANG, Senior EHS Manager, TTM-HY Leo ZAN, EH&S Engineer, Multek Peter ZHOU, Technical Committee Chairman of IPC-1401ESG Management System Standard, IPC | Brief Overview of AI High Speed Digital PCB's Impedance and Loss Measurement Methodology Brian CHI, R&D Manager, Keysight Technologies 因应AI时代高速数字PCB阻抗及损耗测试的挑战 祁子年 — 是德科技股份有限公司 研发经理 |
| 12:00 – 12:30 | ESG圆桌论坛 # 主持: 王乐得 — 思捷环保科技有限公司创办人及行政总裁; 香港线路板协会副会长兼秘书长 嘉宾: 查红平 — 江西红板科技股份有限公司 环境工程部经理 张乾东 — 深圳明阳电路科技股份有限公司 经理 张曦 — TTM-HY 高级经理 咎胜藐 — 珠海斗门超毅实业有限公司 环境健康及安全工程师 周国银 — 国际电子工业联接协会 IPC-1401ESG管理体系标准技术组 主席 | AI is not the Final Solution – a Practical Example of Utilizing Manufacturing Data to Solve Manufacturing Problems Johnson XU, Asia Operations, XACT PCB AI不是最终解决方案— 一个利用制造数据解决制造问题的实际案例 徐啸晨 — XACT PCB 亚太区运营 |
| 12:30 - 13:30 | 午休时间 Lunch Break | |
| 13:30 - 16:30 | 下午议程请见下页。 Please Refer to the Following Page for the Afternoon Agenda. | |

Conference duration is 45 mins

#会议时间为45分钟





INTERNATIONAL ELECTRONICS
CIRCUIT EXHIBITION (SHENZHEN)
国际电子电路(深圳)展览会

Technical Conference 技术会议

CONFERENCE AGENDA 会议议程

2024.12.05 Thursday (星期四)

| Time 时间 | International Technical Conference 国际技术会议 (Hall 6) | Smart PCB: AI Trends & Innovations Conference 智造PCB: AI趋势与创新技术会议 (Hall 5) |
|---------------|---|--|
| 13:30 – 14:00 | Introduction to Energy PCB Products and Technologies Hong FAN, Senior R&D Manager, Aoshikang Technology Co., Ltd. Seegem, Sundell 能源类PCB产品与技术简介 范红 — 奥士康科技股份有限公司, 广东喜珍电路科技有限公司, 森德科技有限公司高级经理 | |
| 14:00 – 14:30 | IC Substrates International Standard Development of IPC-6921 Shine YANG, Standard Manager, IPC IPC-6921封装基板国际标准的开发 杨亮亮 — IPC国际电子工业联接协会标准部门经理 | The Impact and Changes of Artificial Intelligence on PCB Dana PENG, Chairman, Jiangxi Dongxun Precision Manufacturing Co., Ltd., Technical Director of Hunan PCB Association 人工智能对PCB的影响和改变 彭三军 — 江西东讯精密制造有限公司董事长, 湖南线路板协会技术主任 |
| 14:30 – 15:00 | Application of Advanced Insoluble Anode in Modern Cu Electroplating Technology Dr. Jianjun YANG, Electrode Specialist and Advisor, De Nora Italy Singapore Branch 新型不溶性阳极在现代镀铜技术中的应用 杨建军博士 — 意大利迪诺拉公司新加坡分公司 电极专家和顾问 | Application of Artificial Intelligence and Computational Chemistry for Interconnect Electroplating of Printed Circuit Copper Dr. Yuanming CHEN, Associate Professor, University of Electronic Science and Technology of China 印制电路铜互连电镀的人工智能与计算化学应用 陈苑明博士 — 电子科技大学副教授 |
| 15:00 – 15:30 | Rogers Commercial Radar Material Overview and New Product Introduction Phoebe GAO, Market Development Manager, Rogers 罗杰斯商业雷达材料概览及新产品发布 高菲 — 罗杰斯公司市场开发经理 | Challenges of AI PCBs and Reliability Assessment Methods Tom YUAN, CTO, ShenZhen 863 New Material Technology Co., Ltd. AI产品对PCB的挑战与可靠性评估方法 苑旺 — 深圳市八六三新材料技术有限责任公司技术总监 |
| 15:30 – 16:00 | Interaction and Optimization of Direct Metallization and Copper Plating Steps Albert TSENG, Product Manager, MacDermid Alpha Electronics Solutions 直接金属化制程以及酸铜电镀制程的最佳化研究 曾仁宏 — 麦德美爱法电子解决方案产品经理 | Technology Trends and High-Speed Material Solutions for AI Age Roy HUA, Electronic Material Marketing Dept. Senior Manager, Panasonic Industry (China) Co., Ltd. AI时代下的技术趋势以及高速材料解决方案 华炎生 — 松下电器机电(中国)有限公司 电子材料市场部高级经理 |
| 16:00 – 16:30 | BEIJIA Graphite Nano Process Hotspot Application and Development Trend Jin HUANG, Director, Shenzhen Beijia Electronic Materials Co., Ltd. 贝加黑影®工艺热点应用之发展趋势 黄金 — 深圳市贝加电子材料有限公司总监 | Opportunity & Challenge of Generative AI Driven PCB Market Daniel CHAN, Professional PCB Solution, Wellink 生成式AI PCB市场的机遇与挑战 陈锦标 — 维文信专业PCB解决方案专家 |

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AI Powers the Future
AI成就未来

SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 6

PCB Market and Technology Developments for AI Server Systems

AI服务器系统的PCB市场和技术发展

11:00 – 11:45

Hall 6

Dr. Shiu-Kao CHIANG, Managing Partner, Prismark

姜旭高博士 — Prismark合作伙伴

Dr. Shiu-Kao Chiang has a B.Sc., M.S., Executive M.B.A., and a Ph.D. in Ceramic Engineering from Ohio State University. Shiu-Kao's past experience includes material characterization, new product and process development, R&D management and technical marketing. Shiu-Kao holds several patents, awards, and publications in electronic material, packaging, and processing areas. He joined Prismark in February 1998. Dr. Shiu-Kao Chiang is responsible for the development of Prismark's business in Asia, as well as the management of research projects and services in Japan, Taiwan, China, Korea, Singapore, and other Asian countries. Over the past 20 years, Prismark has developed business and service relationships with most of the leading electronics, semiconductor, packaging, assembly, PCB and material companies in Asia. In addition, Prismark has also extended its services to leading financial institutions to assist their investments in Asia.

姜旭高博士，拥有台湾国立清华大学材料科学与工程学士学位，美国NotreDame大学冶金工程硕士学位，美国俄亥俄州（Ohio）州立大学陶瓷工程博士学位，以及美国俄亥俄州克利夫兰州立大学高级工商管理硕士学位。在电子产业里对材料特性，新产品和流程工艺发展，研发管理，以及技术市场有着丰富的经验。他在电子材料，封装，和流程工艺领域拥有专利，奖项，和专业论文。他在1998年2月成为Prismark合伙人。主要负责Prismark在亚洲市场的开发，以及从事对日本，台湾，中国大陆，韩国，新加坡，和其他亚洲国家电子产业的研究。在过去的几十年里，Prismark在电子，半导体，封装，组装，PCB，和材料领域已和很多公司建立合作和服务关系。另外，Prismark也为亚洲主要金融机构提供投资方面的咨询和服务。



Technology Status and Quality Challenges of Communication PCB

通讯产品PCB技术动态和质量挑战

11:45 – 12:30

Hall 6

Fulin ZENG, Senior Engineer and Senior Technical Quality Expert, ZTE

曾福林 — 中兴通讯高级工程师，技术质量资深专家

Zeng Fulin, Senior Engineer, Senior Technical Quality Expert of ZTE. Mr. Zeng has been engaged in PCB material management and technical research for more than 20 years, he is familiar with PCB and PCBA processes. More than 20 papers written by Mr. Zeng have been published in "Electronic Process Technology", and a book "Basic Knowledge of Communication Products PCB and its Application" written by Mr. Zeng was published by Electronic Process Publishing House, which won the 2021 Excellent best seller Award of Electronic Industry Publishing House Co., Ltd.

曾福林，高级工程师，中兴通讯技术质量资深专家，从事PCB材料管理及技术研究工作20多年，熟悉PCB及PCBA加工流程。在《电子工艺技术》上发表论文20余篇，电子工业出版社出版书籍一册《通信产品PCB基础知识及其应用》，荣获电子工业出版社有限公司2021年度优秀畅销书奖。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 6

A New Flex Electroless Nickel Chemistry for ENIG and ENEPIG Applications FPC专用的化镍金或镍钯金制程：新型软镍药水

13:30 – 14:30
Hall 6

Ryan TAM, Business Director, MacDermid Alpha Electronics Solutions 谈国志— 麦德美爱法电子解决方案业务总监

Ryan Tam, takes the role of the Business Director of MacDermid Alpha Circuitry Solutions. After university graduation in 1997, joined in Alpha Metal PC Fab Division (now MacDermid Alpha Circuitry Solutions) and started his service in the PCB industry. Starting as the Product Application Engineer and now Technical Business Development Director, in the past 27 years the work is focusing in the PCB final finish products applications, management & business developments.

Ryan Tam, 现担任麦德美爱法电子线路解决方案业务总监。从1997年大学毕业后入职 Alpha Metal PC Fab Division (即现今的 MacDermid Alpha Circuitry Solutions) 便开始服务 PCB 行业。最开始从事产品应用工程师到现在的技术业务发展总监，过去27年一直都专注在 PCB 表面处理产品的应用、管理和相关业务发展。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 6

On-device AI Supports New Development Opportunities for PCB Development 端侧AI助力PCB发展新机遇

14:30 – 15:00
Hall 6

Vincent WANG, Group Technical Director, Shenzhen Kinwong Electronic Co., Ltd.
王俊 — 深圳市景旺电子股份有限公司集团技术总监

Kinwong Group Technical Director, Senior Engineer, local leading talents in Shenzhen, high-level scientific and technological innovation talents in Bao'an District, Chief Engineer in Bao'an District, Director of Guangdong Province High reliability Automotive printed circuit Board Engineering Technology Research Center, Deputy director of Heyuan City high density and high heat dissipation circuit board enterprise Key Laboratory.

Engaged in PCB industry for more than 20 years, Proficient in PCB design, High-Tech Process, with rich experience in R&D and technology management, leading millimeter-wave radar and other key product development, technological innovation projects, until now, more than 100 patents have been applied for, authorized 94 authorized invention patents and 2 US patents. The project has won the first prize of Shenzhen Science and Technology Progress, the first prize of China Machinery Industry Science and Technology, and the Bao'an District Science and Technology Progress Award, and 11 technologies have received international advanced and domestic leading evaluations.

技术总监，高级工程师，深圳市地方级领军人才，宝安区高层次科技创新人才，宝安区首席工程师，广东省高可靠性汽车印制电路板工程技术研究中心主任，河源市高密度高散热电路板企业重点实验室副主任，从事线路板行业20余年，精通PCB客户端设计、高尖新线路板制造工艺，具有丰富的研发、技术管理经验，主导毫米波雷达等多个重点产品开发、技术创新项目，截止目前申请100多项专利，其中授权发明专利94项，2项美国专利；主持项目先后荣获深圳市科技进步一等奖，中国机械工业科学技术一等奖、宝安区科技进步奖，11项技术获得国际先进、国内领先。



The Driving Forces and Prospects of IC Packaging Substrate Development IC封装基板发展驱动力与前景

15:00 -15:30
Hall 6

Dr. Rambo SUN, PH.D/CTO, Bomin Electronics Co., Ltd.
孙炳合博士 — 博敏电子股份有限公司首席技术官

Dr. Rambo Sun graduated from Shanghai Jiao Tong University in 2005 with a major in Materials Science and is currently the Chief Technology Officer (CTO) of Bomin Electronics Co., Ltd. He has previously worked for well-known domestic and international companies such as ASE Group, SMST-SP, and AT&S etc. focusing on the R&D of electronic circuit products and customer technical support. He has been recognized as a "Double Innovation Talent" and has been appointed as an Industrial Professor for Graduate Student Supervisors in Jiangsu Province.

孙炳合博士，2005年毕业于上海交通大学材料学专业，现任职博敏电子首席技术官；曾先后就职于日月光半导体、美维科技、奥特斯等国内外知名企业，一直从事电子电路产品研发及客户技术支持等相关工作。获评江苏省“双创人才”，受聘江苏省研究生导师类产业教授等。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 6

Challenges and Solutions for PCB Manufacturing Posed by 224G High-Speed Signals

15:30 – 16:00
Hall 6

224G高速信号对PCB制造提出的挑战及解决方案

Dr. Yuuta TANG, Technical Expert, Zhuhai Founder Technology High Density Electronic Co., Ltd.

唐耀博士 — 珠海方正科技高密电子有限公司技术专家

Ph.D. from University of Electronic Science and Technology of China, IC professional senior engineer, innovation engineer level 2. Master's off-campus tutor of the University of Electronic Science and Technology of China, member of the editorial board of "Printed Circuit Information". He joined Founder PCB in 2016 to work on PCB materials, signals integrity, new technology development and application. Now serves as a technical expert of Zhuhai Founder PCB Research Institute. He has long term cooperation with the domestic and foreign core technical teams of leading enterprises in the communication industry chain, to develop forward-looking innovative technologies. He has rich experience in Design, high-speed SI and new technology development of PCB. He has participated in the formulation of one national military standard and one industry standard, published 16 papers (4 SCI papers), and authorized 12 patents. In 2019, he won the third prize of Huawei Six Sigma Black Belt Project, the first prize of Chongqing Innovation Method Competition and the second prize of Guangdong Province Science and Technology Progress Award. In 2020, he won the first prize of China Nonferrous Metals Industry Science and Technology Award. In 2021, he won the first prize of Zhuhai City Science and Technology Progress Award and Huawei Technology Breakthrough Award. In 2022, he won the second prize of Guangdong Province Science and Technology Progress Award. He was awarded "Young Science and Technology Star of PCB Industry" and "Innovation Talent" of Guangdong Province Enterprises. In 2023, he was awarded "The Most Beautiful Science and Technology Worker" in Zhuhai. He strives to practice the independent innovation and domestic substitution of advanced PCB technology.

电子科技大学博士，集成电路专业正高级工程师，创新工程师2级。兼任电子科技大学硕士校外导师，《印制电路信息》编委会委员。2016年进入方正PCB从事印制电路材料、信号、新技术开发及应用方面工作。现担任方正PCB研究院技术专家，长期与国内外通信行业龙头企业及产业链上下游企业及高校核心技术团队合作开发前瞻性创新技术，在印制电路设计、高速信号完整性及印制电路新工艺开发方面经验丰富。曾参与1项国军标及1项行业标准制定，发表论文16篇（SCI 4篇），授权专利12项。2019年获华为六西格玛黑带项目获三等奖、重庆创新方法大赛一等奖及广东省科技进步二等奖，2020年获中国有色金属工业科学技术一等奖，2021获珠海市科技进步一等奖及华为技术突破奖，2022年获广东省科技进步二等奖，被评为“PCB行业青年科技之星”及广东省企业“创新达人”，2023年被评为珠海市“最美科技工作者”。坚持并努力实践先进印制电路技术的自主创新和国产替代。





SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 6

Study on the Influence of PCB Solder Resist Materials on Solder Joint Formation Quality PCB阻焊材料对焊点成型质量的影响研究

16:00 – 16:30
Hall 6

Li ZHAO, Senior Process Expert and Project Manager, ZTE Corporation
赵丽 — 中兴通讯股份有限公司工艺资深专家、项目经理

Li Zhao, a Master's Degree holder, is a Senior Process Expert and Project Manager at ZTE Corporation. She has 15 years of research experience in printed circuit board design and assembly, as well as experience in handling complex issues related to electronic assembly processes. She has participated in three provincial and ministerial-level scientific research projects, won the first prize for scientific and technological progress in the Guangdong Province's electronics and information industry, and holds four authorized patents. Zhao Li joined ZTE Corporation in 2009 and has been engaged in the research of printed circuit board (PCB) process, providing comprehensive solutions for PCB design and assembly for communication products.

赵丽，硕士，中兴通讯股份有限公司工艺资深专家、项目经理，具有15年印制电路板设计与组装研究经验，以及电子装联工艺疑难问题处理经验。参与省部级科研项目3项，获广东省电子信息科技进步一等奖，授权专利4项。从2009年加入中兴通讯股份有限公司，从事印制电路板工艺研究，为通讯产品能提供印制电路板设计与组装综合解决方案。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 5

One Digital Foxconn Towards the AI Era 迈向AI世纪的One Digital Foxconn

11:00 – 11:30
Hall 5

Jin LI, Senior Manager, Foxconn Technology Group
李锦光 — 富士康科技集团 资深经理

- 30+ years of experience in enterprise management, senior manager of overseas Smart Manufacturing Platform Technology Center
- Formulator of the Lighthouse Assessment System
- Expert of IPC technical group of Multi international standards
- 拥有30+年企业管理经验, 海外智能制造平台技术中心高级经理
- 集团灯塔工厂评价体系制定人
- IPC多个国际标准技术组专家



AI-era Dell Accelerates Electronic PCB Industry from Idea to Innovation AI时代戴尔科技加快电子PCB行业从构想到实现创新

11:30 – 12:00
Hall 5

Richard LI, Senior Manager, Dell Technologies
李炜 — 戴尔科技集团 终端产品组合作伙伴与行业方案业务高级经理

Having been with Dell Technologies for 24 years. Served in various departments including IT, Marketing, and Product Group. Dedicated to the IT infrastructure, computing platforms, and industry solutions. Also focus on the implementation of projects with partners in the Chinese market.

加入戴尔科技集团24年, 曾服务于戴尔科技多个业务部门, 包括信息技术部, 市场部, 产品部等, 长期专注于IT基础架构, 算力平台及各行业解决方案的研究, 并关注与各合作伙伴在中国市场的项目落地。



Artificial Intelligence – Design and Manufacturing Opportunities and Challenges in the PCB Industry*

12:00 – 12:30
Hall 5

人工智能—PCB行业设计及制造的机遇和挑战*

Erkko HELMINEN, Senior Manager of Commercial Technology, TTM Technologies
Erkko HELMINEN — TTM集团 商用技术部高级经理

Mr. Erkko Helminen has a Master's Degree in Electrical Engineering, he is a Senior Manager of Commercial Technology at TTM Technologies, Inc. Mr. Helminen is responsible for process development. With 20 years' experience in the PCB industry, Mr. Helminen has wide experience from HDI to MLB technologies including process technologies, reliability and failure analysis, as well board level signal integrity.

Erkko Helminen先生拥有电气工程硕士学位, 他是TTM集团商用技术部高级经理。Erkko Helminen先生负责工艺开发。他在PCB行业有20年的经验, 从HDI到多层板技术经验广泛, 包括工艺技术、可靠性和故障分析, 以及板级信号完整性分析。



* Conference to be conducted in English
*会议以英文进行

SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 5

Artificial Intelligence and PCB Outlook: Computing as the Foundation and Application as the Spear

14:00 – 14:30
Hall 5

人工智能与PCB展望：算力为基，应用为矛

Jack DING, Senior Vice President Research Dept, CITIC Securities

丁奇 — 中信证券研究部高级副总裁

Senior Vice President of the Research Department of CITIC Securities. Youth science and innovation consultant of Tsinghua University. Once worked at Huawei and China Unicom. Familiar with fields such as artificial intelligence, electric vehicles, and communications. Published well-known best-selling books in the communications industry such as "Joking about Wireless Communication" and "Joking about Mobile Communication" by Posts & Telecom Press. The sales volume exceeds 100,000 copies.

中信证券研究部高级副总裁，清华大学青年科创顾问。曾就职于华为、中国联通，熟悉人工智能、电动汽车、通信等领域。在人民邮电出版社出版《大话无线通信》、《大话移动通信》等通信行业知名畅销书，销量超10万本。



AI Empowers the High-quality Development of the PCB Industry

14:30 – 15:00
Hall 5

AI赋能PCB产业高质量发展

Simon YU, Executive President, Shenzhen Intelligent Manufacturing Industry Promotion Association; Vice President of New Quality Productivity Industry Association of Nanshan District in Shenzhen; Chief Expert of Expert Committee of Internet of Things of China Smart City

喻波 — 深圳市智能制造产业促进会常务会长，深圳市南山区新质生产力产业协会副会长，中国智慧城市建设投资联盟首席物联网专家

Mr Simon Yu has been deeply involved in the development of intelligent technology for many years. Over this time, he has served as a consultant, expert, and judge for numerous universities, state-owned enterprises, think tanks, technology innovation institutions, and technology competitions. With over 25 years of experience, he has worked across various industries, including logistics supply chains, the Internet of Things, robotics, drones, the industrial Internet, industrial research, financial investment, and more. He has held roles such as IT Director, CTO, Vice President, CEO, Dean, and Co-Founder.

喻波先生长期深耕智能科技发展工作，历年来担任多家高校、国央企、智库、科创机构、科创大赛的顾问、专家及评委。超过25年时间工作于物流供应链、物联网、机器人、无人机、工业互联网、产业研究、金融投资等行业，国企、港资世界500强、上市公司及行业龙头担任IT负责人、CTO、副总、CEO、院长、联合创始人等职位。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 5

From Data to Artificial Intelligence: The Transformation Journey of AI Technology in PCB Industry

15:00 – 15:30
Hall 5

从数据到人工智能：AI技术在PCB产业中的转型之路

Harold CHENG, General Manager, PROFET AI
郑诗怀 — 上海颀纶科技软件有限公司总经理

PROFET AI General Manager for Greater China. Focused on serving industries such as semiconductors, automotive, electronic components, and chip design. Previously held positions at several international software companies.

A serial entrepreneur, with experience ranging from app development for application services to IoT-based event management hardware and software, and an investor in healthcare-related software management platforms.

PROFET AI 大中华区总经理。服务行业专注于半导体，汽车，电子零部件，芯片设计等产业，曾任职于多家国际软件外企。连续创业，从应用服务App开发到IoT赛事管理软硬件，投资医疗相关软件管理平台。



Liquid Chromatography-electrochemistry Combined Detection of Plating Solution Additives

15:30 – 16:00
Hall 5

液相色谱-电化学联用检测镀液添加剂

Junwei WU, Postgraduate, School of Chemistry, Sun Yat-sen University
吴俊炜 — 中山大学化学学院硕士研究生

2017.9-2020.6 School of Materials Science, Dongguan University of Technology - Metal Materials Engineering

2023.9 to date School of Chemistry, Sun Yat-sen University - Materials and Chemical Engineering.

2017.9-2020.6 东莞理工学院材料学院-金属材料工程

2023.9至今 中山大学化学学院-材料与化工



Research on Replacing Salt Spray Test with Tafel Test

15:30 – 16:00
Hall 5

塔菲尔测试替代盐雾试验的研究

Haoheng LIU, Postgraduate, School of Chemistry, Sun Yat-sen University
刘浩衡 中山大学化学学院硕士研究生

2020.9-2024.6 School of Electronics and Information Technology, Sun Yat-sen University - Electronic Information Science and Technology

2024.9 to date School of Chemistry, Sun Yat-sen University - Materials and Chemical Engineering

2019.9-2023.6 中山大学电子与信息工程学院-电子信息科学与技术

2023.9至今 中山大学化学学院-材料与化工





INTERNATIONAL ELECTRONICS
CIRCUIT EXHIBITION (SHENZHEN)
国际电子电路(深圳)展览会

Technical Conference 技术会议

SPEAKER BIOGRAPHY 演讲者介绍

2024.12.04 Wednesday (星期三) Hall 5

AI Accelerates PCB Pre-manufacturing Engineering Design and Precise Quotations

**16:00 – 16:30
Hall 5**

AI 赋能PCB制前工程设计和精準報價

Towers GUO, General Manager, Shenzhen Yimeike Software Co., Ltd.,
郭套山 — 深圳市易美科软件有限公司总经理

Education: Bachelor's degree, School of Management, Harbin Institute of Technology; Lingnan College, Sun Yat-sen University, Master of International Business Administration.

Work Experience: Founder of Shenzhen Yimeike Software Co., Ltd., affiliated to Guangzhou SIE Information Technology Co., Ltd.

教育背景: 哈尔滨工业大学管理学院, 本科学士学位; 中山大学岭南学院, 国际工商管理硕士学位。

工作经历: 深圳市易美科软件有限公司创始人, 隶属于广州赛意信息科技股份有限公司。



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AI Powers
the Future
AI成就未来

SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

Implementation of Carbon Trading and ESG in China and Overseas Markets 国内外碳权交易与ESG推行的执行方案

10:30 – 11:00
Hall 6

Prof. Felix CHUNG, Adjunct Professor in the Chinese University of Hong Kong and City University of Hong Kong, HKCTC Founder

钟国斌教授 — 香港中文大学及香港城市大学兼任教授；香港碳贸易中心创办人

Prof. Felix Chung is currently an Adjunct Professor in the Chinese University of HK (Department of Government and Public Administration) and City University of HK (Department of Public and International Affairs of the College of Liberal Arts and Social Sciences); Member of Carbon Market Opportunities Working Group of Financial Services Development Council (FSDC); Founding Member of CE100 HK; Honorary President of HK Association of Solar Energy Industry etc. ; Founder & CEO of Hong Kong Carbon Trading Centre (HKCTC). HKCTC helps all kind of industrial companies to reduce carbon emission to minimize World's global warming and climate change.

钟国斌教授是香港中文大学政治与行政学系及香港城市大学人民社会科学院公共及国际事务学系兼任教授，金融发展局碳市场机遇工作小组成员，洁能100/零碳100创始成员，香港太阳能应用协会荣誉会长等。2022年创办香港碳贸易中心(HKCTC)并担任首席执行官，HKCTC 主要协助各类型工业企业提供减少碳排放方案以帮助改善全球气温上升及气候变化。



Introduction of LCMP Carbon Reduction Methodology and Samples of Energy Saving Technologies

LCMP低碳制造减碳方法学介绍及节能技术案例

11:00 – 11:45
Hall 6

ESG Panel Discussion Moderator

ESG圆桌论坛主持

11:45 – 12:30
Hall 6

Luther WONG, Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA

王乐得—思捷环保科技有限公司创办人及行政总裁；香港线路板协会副会长兼秘书长

Mr. Luther WONG is the Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA; Vice Chairman of HK Environmental Protection Industry Association(HKEPIA); World Wide Fund for Nature (WWF) Low Carbon Manufacturing Plan (LCMP) Appeal Board Member; Former MD of Electronic Materials BU of DuPont (Dow /Rohm & Haas /LeaRonan) (Resigned in 2001 to form environmental protection company); Standing Committee Member of CPPCC Liaoning Province/Convener of Hong Kong Region; HK Justice of the Peace.

王乐得先生，思捷环保科技有限公司创办人及行政总裁，香港线路板协会副会长兼秘书长，香港环保产业协会副主席，WWF低碳制造计划(LCMP)上诉委员会委员，杜邦（陶氏/罗门哈斯/励乐）电子材料亚洲区的前行政总裁(2001年离任创办C&G环保公司)，辽宁省政协常委/港区召集人，香港太平绅士。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

ESG Panel Discussion Guests

ESG圆桌论坛嘉宾

11:45 – 12:30

Hall 6

Hongping ZHA, Environment Engineering Department Manager, Jiangxi Redboard Technology Co., Ltd.

查红平 — 江西红板科技股份有限公司 环境工程部经理

Manager of Environmental Engineering Department (EED) of Jiangxi Redboard Technology Co., Ltd.; Professorate Senior Engineer of Ecological Environmental Engineering and Construction; Master of Environmental Engineering of Nanchang University; Bachelor of Applied Chemistry of Chengdu University of Technology;

16-year experience in environmental management, pollution control and cleaner production; holding eight (8) granted invention patents and over forty (40) utility model patents; published nine (9) papers and one (1) monograph; listed Jiangxi Province-level Top-notch Talents (Bai-Qian-Wan); cleaner production audit expert of Jiangxi Provincial Department of Ecology and Environment; specialist in solid waste environmental management; specialist environmental consultant of Hong Kong Printed Circuit Association.

江西红板科技股份有限公司 环境工程部经理，生态环境工程与建设正高级工程师，南昌大学环境工程硕士、成都理工大学应用化学学士。

从事环保管理、污染治理和清洁生产工作16年，授权发明专利8项、实用新型专利40余项、发表论文9篇、编写专著1篇。入选“江西省百千万人才”人选、江西省生态环境厅清洁生产审核专家和固体废物环境管理专家库，香港线路板协会特聘环保顾问。



ESG Panel Discussion Guests

ESG圆桌论坛嘉宾

11:45 – 12:30

Hall 6

Qiangdong ZHANG, Manager, Sunshine Global Circuits Co., Ltd.

张乾东 — 深圳明阳电路科技股份有限公司 经理

Mr. Zhang grew up with Sunshine Global Circuits Co., Ltd. and was mainly responsible for ESG information disclosure, ISO14067 product carbon footprint, and ESG direct/pan-related. In addition, he is responsible for the analysis of climate change trends, customer carbon requirements (Apple, Bosch, Microsoft, etc.), and supply chain carbon reduction project analysis.

同明阳电路一起成长，主要负责 ESG 信息披露、ISO14067 产品碳足迹，ESG 直接相关/泛相关工作。此外还负责应对气候变迁之趋势分析、客户碳要求（Apple、Bosch、Microsoft 等等）、供应链减碳项目分析。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

ESG Panel Discussion Guests

ESG 圆桌论坛嘉宾

11:45 – 12:30

Hall 6

KK ZHANG, Senior EHS Manager, TTM-HY

张曦 — TTM-HY 高级经理

Environmental Engineer Major at college, Master of Engineering Science

KK have more than 20 years of EHS work experience in PCB industry, that are responsible for the managing of environmental, facility and energy consumption. And have rich practice experience in planning, implementing and program developing of ESG initiatives within organization.

环境工程专业，硕士研究生

近20年PCB行业EHS从业经历，负责企业的环境、设施、能源相关的管理工作，对企业ESG策略应对、绩效建立和实施有丰富的实践经验。



ESG Panel Discussion Guests

ESG 圆桌论坛嘉宾

11:45 – 12:30

Hall 6

Leo ZAN, EH&S Engineer, Multek

咎胜藐 — 珠海斗门超毅实业有限公司 环境健康及安全工程师

Currently employed at Multek., the company specializes in manufacturing multi-layer PCBs. Primarily responsible for the compliant management of the company's wastewater, waste gas, and solid waste, ensuring the normal operation and maintenance of environmental protection facilities and the compliance of related pollutants with standards. I handle environmental protection compliance procedures, oversee the compliant operation of the environmental protection platform, respond to inspections by regulatory authorities, and make timely improvements.

现就职珠海斗门超毅实业有限公司，公司主营PCB多层线路板。主要负责公司废水、废气、废物的合规化管理，保障环保处理设施的正常运维，以及相关污染物的达标。办理环保合规化手续，负责环保平台合规运行，应对监管部门检查并及时改善。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

ESG Panel Discussion Guests

ESG 圆桌论坛嘉宾

11:45 – 12:30

Hall 6

Peter ZHOU, Technical Committee Chairman of IPC-1401 ESG Management System Standard, IPC

周国银 — 国际电子工业联接协会 IPC-1401 ESG 管理体系标准技术组主席

Mr. Peter Zhou acts as the technical committee chairman of IPC-1401 ESG management system standard since 2014, he leads to develop and revised the "ISO9001 standard of ESG sector", which re-defines ESG as customer requirements and the features of products and business activities, helps manufacturers focus on ESG pain points and transform external ESG issues to manageable issues as a part of business competitiveness strategies and daily operations. In 2023 and 2024 he has led corporate top 10 ESG hot points and pain points survey.

Mr. Zhou has more the 30 years professional experiences in the field of corporate ESG, he had established the global procurement ESG systems of Huawei, Best Buy, Puma and SGS, his 5 ESG innovational cases were awarded as best practices of UNGC and JAC, he received the awards of 2019 ICT ESG manager, 2023 IPC Asia best leadership and 2024 Sedex influential people, he published 4 ESG books including translation of the first ESG book The Social Responsibility of Businessman.

周国银先生2014年至今担任国际电子工业联接协会IPC-1401 ESG管理体系标准技术组主席，领导制定并修订“ESG领域ISO9001标准”，从企业视角重新定义ESG为客户要求以及产品属性和商业活动的属性，协助企业聚集ESG痛点，将外部ESG议题转化为可管理议题，将ESG融入企业竞争战略和日常运营。他领导完成2023年和2024年企业ESG十大热点十大痛点调查。

周先生从事企业ESG专业管理30多年，先后主导建立华为、百思买及彪马等企业全球采购ESG尽责管理体系，他的5个ESG创新项目获得联合国全球契约和全球电信行业JAC优秀实践奖，它还获得2019电子行业ESG经理人奖，2023IPC亚洲最佳领导奖及2024SEDEX影响力人物奖，他出版4本ESG专著包括引进出版ESG开山之作《商人的社会责任》。



Introduction to Energy PCB Products and Technologies

能源类PCB产品与技术简介

13:30 – 14:00

Hall 6

Hong FAN, Senior R&D Manager, Aoshikang Technology Co., Ltd.

Seegem, Sundell

范红 — 奥士康科技股份有限公司，广东喜珍电路科技有限公司，森德科技有限公司高级经理

Fan Hong, Senior Engineer in Electronic Technology, majoring in Applied Chemistry, holds a Master's degree. The current Senior R&D Manager at Aoshikang Technology Co., Ltd. specializes in materials, SI, high-speed PCB development and production conversion, as well as environmental protection and intellectual property management.

范红，电子技术高级工程师职称，应用化学硕士研究生学历，现任奥士康科技股份有限公司高级研发经理，擅长材料、SI、高速PCB开发与生产转化工作，以及环保与知识产权管理工作。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

IC Substrates International Standard Development of IPC-6921

IPC-6921封装基板国标标准的开发

14:00 – 14:30

Hall 6

Shine YANG, Standard Manager, IPC

杨亮亮 — IPC国际电子工业联接协会 标准部门经理

IPC China Standards Manager, graduated from Nanjing University of Aeronautics and Astronautics, with 9 years of experience in PCB/FPC manufacturing and process. Worked for IPC from 2016 as Standards Manager, mainly responsible for the development and maintenance of IPC PCB-related standards; and served as IPC-A-600 standard training MIT.

IPC中国标准部门经理，毕业于南京航空航天大学，拥有9年PCB/FPC制造和工艺经验。于2016年加入IPC担任标准部门经理，主要负责IPC PCB相关标准的开发和维护；担任IPC-A-600培训MIT。



Application of Advanced Insoluble Anode in Modern Cu Electroplating Technology

新型不溶性阳极在现代镀铜技术中的应用

14:30 – 15:00

Hall 6

Dr. Jianjun YANG, Electrode Specialist and Advisor, De Nora Italy Singapore Branch

杨建军博士 — 意大利迪诺拉公司新加坡分公司电极专家和顾问

2024.10 – 1998.8: De Nora Italy Singapore Branch, Managing Director

1998.7 – 1995.5: Heraeus Electrochemie, Germany and Hong Kong, Sales and Technical Manager

1994.11 – 1988.11: Ph D study at University of Freiburg, Germany “Electrochemical study on photosensitive dyestuff, new donor-acceptor compounds for organic magnet by using of ultra micro electrode”

1988.8 – 1985.9: Lecture at Central South University, China, “Metallurgical electrochemistry”

1985.7 – 1978.10, Bachelor’s and Master’s degree at Central South University, China, “Physical chemistry of metallurgy”

2024.10 – 1998.8: 意大利迪诺拉公司新加坡分公司总经理

1998.7 – 1995.5: 德国贺利氏电化学公司香港分公司销售技术经理

1994.11 – 1988.11: 中国国家教委奖学金得主于德国弗莱堡大学物理化学研究所攻读电化学博士学位，论文主题“超微电极方法研究感光染料分子之光电属性和新型有机铁磁体之供体-受体化合物”

1988.8-1985.9: 中国中南大学教师，主讲冶金电化学

1985.7 – 1978.10: 中国中南大学化学系攻读学士和硕士学位，主修冶金物理化学



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 6

Rogers Commercial Radar Material Overview and New Product Introduction

罗杰斯商业雷达材料概览及新产品发布

15:00 – 15:30

Hall 6

Phoebe GAO, Market Development Manager, Rogers

高菲 — 罗杰斯公司市场开发经理

Phoebe Gao is Market Development Manager in Rogers and responsible for the development and expansion of PCB materials in the wireless communication and automotive mm-Wave radar markets, as well as the demand for new materials. Graduated with a master degree from Xi'an University of Electronic Science and Technology and have worked in Huawei's wireless RF R&D department, Phoebe could better understand customers' needs and help them utilize the Rogers materials with years of R&D experience.

高菲是罗杰斯公司的市场开发经理，主要负责PCB材料在无线通信及汽车毫米波雷达市场的开发及拓展、新材料需求等方面的工作。高菲硕士研究生毕业于西安电子科技大学，曾就职于华为无线射频研发部门，多年的研发经验可更好地理解客户的需求，帮助客户选择和使用罗杰斯材料。



Interaction and Optimization of Direct Metallization and Copper Plating Steps

直接金属化制程以及酸铜电镀制程的最佳化研究

15:30 – 16:00

Hall 6

Albert TSENG, Product Manager, MacDermid Alpha Electronics Solutions

曾仁宏 — 麦德美爱法电子解决方案产品经理

Albert Tseng is the Product Manager of Metallization for MacDermid Alpha. Albert works for the metallization processes of the PCB manufacturing over 25 years. In cooperation with partner manufacturers, Albert has successfully applied the direct metallization process to the metallization process of Any-Layer HDI PCBs for the mainboard of smartphones. Also successfully apply the direct metallization process to the metallization process of HDI Flex PCBs for variety of electronic devices.

Albert Tseng, 现担任金属化工艺产品经理，从事印刷电路板金属化制程相关工作超过25年。Albert与合作厂商共同合作，成功的将直接金属化制程应用于生产高信赖性的多层高密度互联的手机主板，更采用直接金属化制程成功的让高密度互联软板以更环保、符合ESG环境永续的方式，完成软板高难度的金属化需求。



BEIJIA Graphite Nano Process Hotspot Application and Development Trend

贝加黑影®工艺热点应用之发展趋势

16:00 – 16:30

Hall 6

Jin HUANG, Director, Shenzhen Beijia Electronic Materials Co., Ltd.

黄金 — 深圳市贝加电子材料有限公司总监

Mr. Huang has been engaged in technical of PCB industry for 15 years, mainly engaged in PCB manufacturing technology and applications of related electronic chemical. Be familiar with manufacturing via hole shadow by Flexible PCB, Rigid-Flex PCB and Rigid PCB, and matching process.

黄金先生在PCB行业从事技术工作15年，主要从事于PCB制造技术和相关电子化学品应用，对于PCB软板、软硬结合板及硬板制造导通孔之黑影工艺及前后搭配工艺应用有较丰富经验。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 5

IPC Factory of the Future Standards Empower - AI-enabled PCB Manufacturing IPC未来工厂标准助力AI赋能PCB生产

10:30 – 11:00
Hall 5

Chuck LI, Standards Director, IPC
李金山 — IPC国际电子工业联接协会 标准总监

Joined IPC in 2013 and currently serves as the Director of Standards, primarily responsible for the development of IPC's digitalization-related standards and the implementation of IPC Factory of the Future standards in Asia.

2013年入职IPC，现担任标准总监，主要负责IPC数字化相关标准的开发以及IPC未来工厂相关标准在亚洲的落地实施。



PCB Process and Simulation Analysis of AI Products AI产品的PCB工艺与仿真分析

11:00 – 11:30
Hall 5

Gang HUANG, SI Research Manager, Shenzhen Edadoc Technology Co., Ltd.
黄刚 — 深圳市一博科技股份有限公司SI研究部经理

Mr. Huang Gang, responsible for SI theory research, technology development and internal and external training exchanges; good at simulation and optimization for high-speed communication system design, test fixture design, simulation and measurement calibration. He has received dozens of SI-related patents and is the main author of "Easy High-speed's articles.

黄刚先生，负责SI理论研究，技术开发及对内外培训交流；擅长高速通信系统设计仿真优化，测试夹具设计及仿真与测试校准交互；获得数十项SI相关专利，也是高速先生文章的主要撰写人。



Brief Overview of AI High Speed Digital PCB's Impedance and Loss Measurement Methodology

11:30 – 12:00
Hall 5

因应AI时代高速数字PCB阻抗及损耗测试的挑战

Brian CHI, R&D Manager, Keysight Technologies
祁子年 — 是德科技股份有限公司研发经理

Brian joined Agilent/Keysight Technologies as an Application Engineer since 2000 and transferred to R&D in 2016. His key focusing areas are unlicensed wireless Wi-Fi regulatory verification system, optical and electrical high-speed digital communication test solutions. He served as an external lecturer at Tsinghua University Foundation and National Taiwan University of Science and Technology, also published many technical articles in New Communications and Electronic magazines.

祁子年先生2000年加入安捷伦/是德科技担任应用工程师，于2016年转任研发，主要支持领域为无线Wi-Fi法规验证；光、电高速数字通讯测试方案。曾任清华大学自强基金会及台湾科技大学外聘讲师，并在新通讯、电子杂志期刊发表多篇技术文章。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 5

AI is not the Final Solution – a Practical Example of Utilizing Manufacturing Data to Solve Manufacturing Problems

12:00 – 12:30
Hall 5

AI 不是最终解决方案— 一个利用制造数据解决制造问题的实际案例

Johnson XU, Asia Operations, XACT PCB
徐啸晨— 亚太区运营, XACT PCB

Mr. Xiao Chen Xu (Johnson), Operations for XACT PCB Asia, Degree of International Master of Business Administration (IMBA) from Xi'an Jiaotong-Liverpool university, nearly 15 years of experiences in PCB manufacturing industry, joined XACT PCB in 2014, enabled leading Asia PCB fabricators to achieve smart registration systematic manufacturing.

徐啸晨先生, XACT PCB 亚太区负责人, 西交利物浦大学国际工商管理硕士, PCB 制造业近15年经验, 2014年加入XACT PCB 亚太区团队, 协助亚洲众多PCB领先工厂实现对准度智能化制造



The Impact and Changes of Artificial Intelligence on PCB

14:00 – 14:30
Hall 5

人工智能对PCB的影响和改变

Dana PENG, Chairman, Jiangxi Dongxun Precision Manufacturing Co., Ltd.,
Technical Director of Hunan PCB Association

彭三军 — 江西东讯精密制造有限公司 董事长, 湖南线路板协会技术主任

- EMBA of Tsinghua University
- Blue Class of Six Sigma
- Technical Director of Hunan PCB Association
- PCB manufacturing and management experience 25 years
- Senior management experience in Japanese, Hong Kong and domestic PCB listed companies

- 清华大学EMBA工商管理毕业
- 精益六西格玛黑带毕业
- 湖南线路板协会技术主任
- 25年PCB制造和管理经验
- 日资、港资和内资PCB上市公司高级管理经验
- 创建江西东讯精密



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 5

Application of Artificial Intelligence and Computational Chemistry for Interconnect Electroplating of Printed Circuit Copper 印制电路铜互连电镀的人工智能与计算化学应用

14:30 – 15:00
Hall 5

Dr. Yuanming CHEN, Associate Professor, University of Electronic Science and Technology of China

陈苑明博士, 电子科技大学副教授

Dr. Yuanming Chen, Associate Professor at University of Electronic Science and Technology of China. Dr. Chen obtained a doctoral degree and completed post-doctoral fellow at the Postdoctoral Research Station of Electronic Science and Technology. He was the visiting scholar of the Loughborough University, core member of the innovation team of the "Sail Plan" in Guangdong Province. Dr Chen is also a member of National Committee for Printed Circuit Standardization Technology.

Dr. Chen has published more than 100 papers in Electrochimica Acta, Chinese Science: Chemistry and other publications, obtained more than 70 issued Chinese invention patents. Moreover, he also won the second prize of Science and Technology Progress Award of the Ministry of Education in 2022 and the 24th China Patent Excellence Award.

陈苑明博士, 电子科技大学副教授。获电子科技大学博士学位, 以及电子科学与技术博士后流动站博士后。同时是英国Loughborough University访问学者, 广东省「扬帆计划」创新团队核心成员, 全国印制电路标准化技术委员会委员。

陈博士在Electrochimica Acta、中国科学: 化学等刊物发表论文100余篇 (SCI收录论文70余篇); 获授权中国发明专利70多项。技术成果获2022年教育部科技进步二等奖 (排名第1), 2022年第二十四届中国专利优秀奖 (排名第1) 等。



Challenges of AI PCBs and Reliability Assessment Methods AI产品对PCB的挑战与可靠性评估方法

15:00 – 15:30
Hall 5

Tom YUAN, CTO, ShenZhen 863 New Material Technology Co., Ltd.

苑旺 — 深圳市八六三新材料技术有限责任公司技术总监

Master of Engineering, Harbin Institute of Technology, majoring in Materials Engineering; 20 years of experience in the field of reliability and failure analysis of electronic products; worked in Huawei/SGS/ZTE/UL and other well-known enterprises, ZTE Reliability Expert Committee member. He has a deep knowledge of the failure mechanism of electronic product components, and has rich practical experience in failure analysis and reliability testing of electronic machine/PCB/PCBA products; Member of IPC6012, J-020E, 9701, 7095, SM785, AJ820 standard group; 2 national invention patents.

哈尔滨工业大学材料工程专业硕士。专注于电子产品可靠性与失效分析领域20年从业经历。曾就职于Huawei/SGS/ZTE/UL等知名企业, ZTE可靠专家委员会成员。对电子产品组件失效机理具有深刻的认知, 在电子整机/PCB/PCBA产品失效分析与可靠性测试方面具备丰富的实战经验。曾任IPC6012, J-020E, 9701, 7095, SM785, AJ820标准组成员, 申请国家发明专利2项。



SPEAKER BIOGRAPHY 演讲者介绍

2024.12.05 Thursday (星期四) Hall 5

Technology Trends and High-Speed Material Solutions for AI Age

AI时代下的技术趋势以及高速材料解决方案

15:30 – 16:00

Hall 5

Roy Hua, Electronic Material Marketing Dept. Senior Manager, Panasonic Industry (China) Co., Ltd.

华炎生 — 松下电器机电(中国)有限公司电子材料市场部高级经理

In charge of the domestic market development of Panasonic materials, nearly 20 years of experience in the PCB industry and PCB materials market development.

主要负责松下板材的国内市场开发，在PCB行业及材料市场开发方面近20年工作经验。



Opportunity & Challenge of Generative AI Driven PCB Market

生成式AI PCB市场的机遇与挑战

16:00 – 16:30

Hall 5

Daniel CHAN, Professional PCB Solution, Wellink

陈锦标 — 维文信专业PCB解决方案专家

Daniel Chan FMBA, MSC, CPSM, Wellink Professional PCB Solution. 10 Years of IBM Global PCB Procurement Council Chairman, leading IBM global team to source and develop engineering solution of high-end supercomputer server (P&Z series) and their peripheral electronic Inter-connect technology with many global recorded success. First Asian to work with global talented team to develop manufacturing engineering and the design solution of FC-BGA of Power RISC CPU P6 & P7 Former senior leadership roles of globally renowned circuit board production companies, responsible for high-end circuit board production process. technology development and mass production with multiple patents. Former /Current Expert Technical Consultant for China Printed Circuit Board Association / Hong Kong Printed Circuit Board Association / Hong Kong Productivity Council, TianXi, TZTEK, etc.

Daniel Chan, FMBA, 理学硕士, CPSM, Wellink Professional PCB Solution 维文信专业PCB解决方案专家10年IBM全球PCB采购委员会主席，领导IBM全球团队采购和开发高端超级计算机服务器(P&Z系列)的工程解决方案及其外围电子互连接技术，并在全球取得了许多成功。作为第一个亚洲专家与全球人才团队合作开发FC-BGA CPU的制造工程和设计解决方案。曾作为前全球知名电路板生产公司的资深领导角色，负责高端电路板的生产过程、技术开发和量产，拥有多项专利。中国印刷电路板协会/香港线路板协会/香港生产力委员会、天熙、天准等公司的前任/现任专家技术顾问。

